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1. Application

This specification shall be applied to the ESD Protection Device.

- LXES1UBAB1-007
- LXES1UBAA1-096
- LXES1TBCC2-004
- LXES1TBBB2-013
- LXES2SBAA4-016
- LXES2SBBB4-026
- LXES2SBAA4-114
- LXES2TBCC4-028
- LXES4XBAA6-027



2. Part Number Configuration

LXES 1U B AB 1 - 007
 ① ② ③ ④ ⑤ ⑥

- ① Product ID (LXES = ESD Protection device)
- ② Dimension Code

Unit : mm

Code	Dimension	package (serial number)	Code	Dimension	package (serial number)
1U	1.0 x 0.6	DFN1006P2E (007) DFN1006P2X (096)	2T	2.5 x 1.0	DFN2510P10E (028)
1T	1.6 x 1.6	QFN1616P6E (004/013)	4X	4.9 x 3.0	MSOP-8L (027)
2S	2.9 x 2.8	SOT23-6L (016/026) SOT23-5L (114)			

- ③ Type(B:Silicon ESD)
- ④ Control Code
- ⑤ Number of channel
- ⑥ Serial Number

※RoHS Compliant
Halogen free
T/R only.

3. CHARACTERISTICS

3-1 Ratings

Parameter	Package	Operating Temperature	Storage Temperature
Symbol		T _{OP}	T _{STO}
Unit		°C	°C
LXES1UBAB1-007	DFN1006P2E	-40 to +85	-40 to +125
LXES1UBAA1-096	DFN1006P2X	-40 to +85	-40 to +125
LXES1TBCC2-004	QFN1616P6E	-40 to +85	-40 to +125
LXES1TBBB2-013		-40 to +85	-40 to +125
LXES2SBAA4-016	SOT23-6L	-40 to +85	-40 to +125
LXES2SBBB4-026		-40 to +85	-40 to +125
LXES2SBAA4-114	SOT23-5L	-40 to +85	-40 to +125
LXES2TBCC4-028	DFN2510P10E	-40 to +85	-40 to +125
LXES4XBAA6-027	MSOP-8L	-40 to +85	-40 to +125

3-2 Electrical Characteristics (T=25°C)

Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{P_{in1}} =5V, V _{P_{in2}} =0V	I _{br} =1mA, P _{in1} to P _{in2}	Ta=25°C	Ta=25°C	V _{P_{in1,2}} =0V, f = 1MHz, Between Channel pins
LXES1UBAB1-007	+/-17.5	1.0 (max)	18 (min)	+/- 15	+/- 8	0.5
LXES1UBAA1-096	+/-5.5	1.0 (max)	5.8 (min)	+/- 15	+/- 12	8

Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin5} =5V, V _{pin2} =0V, V _{CH} =0-5V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _{pin5} = 5V, V _{pin2} = 0V, V _{IN} = 2.5V, f = 1MHz, Any I/O pin to Ground
LXES1TBCC2-004	+/-5.5	1.0 (max)	6 (min)	+/- 15	+/- 12	0.55

Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin5} =5V, V _{pin2} =0V, V _{CH} =0-5V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _{pin2} = 5V, V _{pin5} = 0V, V _{IN} = 2.5V, f = 1MHz, Any I/O pin to Ground
LXES1TBBB2-013	+/-5.5	1.0 (max)	6 (min)	+/- 15	+/- 12	0.55

Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	VRWM	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin5} =5V, V _{pin2} =0V, V _{CH} =0-5V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _{pin5} = 5V, V _{pin2} = 0V, V _{IN} = 2.5V, f = 1MHz, Any I/O pin to Ground
LXES2SBAA4-016	+/-5.5	1.0 (max)	6 (min)	+/- 15	+/- 10	0.55
LXES2SBBB4-026	+/-5.5	1.0 (max)	6 (min)	+/- 15	+/- 10	1.0

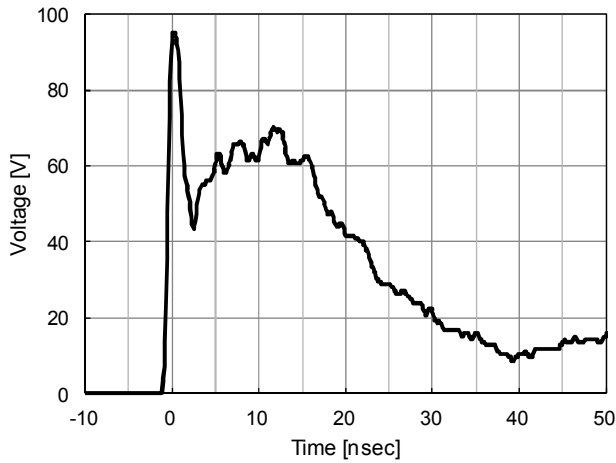
Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin1,3,4,5} =5V, V _{pin2} =0V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _R =0V, f=1MHz
LXES2SBAA4-114	+/-5.0	2.5 (max)	6.1 (min)	+/- 22	+/- 15	12

Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin3,8} =0V, V _{pin1,2,4,5} =0-5V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _{pin3,8} =0V, V _{in} =2.5V, f=1MHz
LXES2TBCC4-028	+/-5.5	1.5 (max)	6 (min)	+/- 15	+/- 10	0.5

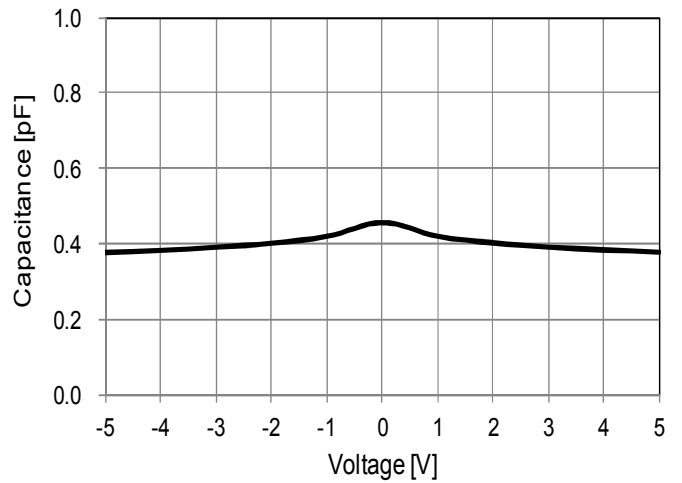
Parameter	Reverse Working Voltage	Channel Leakage Current	Break down voltage	ESD per IEC 61000-4-2(air)	ESD per IEC 61000-4-2 (contact)	Capacitance
Symbol	V _{RWM}	I _{leak}	V _{br}	V _{esd}	V _{esd}	C
Unit	V	uA	V	kV	kV	pF
Condition		V _{pin6} =5V, V _{pin7} =0V, V _{CH} =0-5V	I _{br} =1mA	Ta=25°C	Ta=25°C	V _{pin6} =5V, V _{pin7} =0V, V _{in} =2.5V, f=1MHz
LXES4XBAA6-027	+/-5.5	1.0 (max)	6 (min)	+/- 15	+/- 8	0.27

3-3 Typical Characteristics

LXES1UBAB1-007

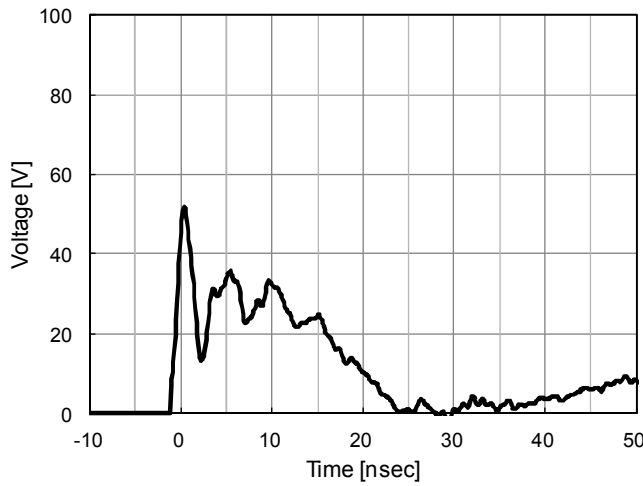


ESD Waveform(IEC61000-4-2:8kV Contact)

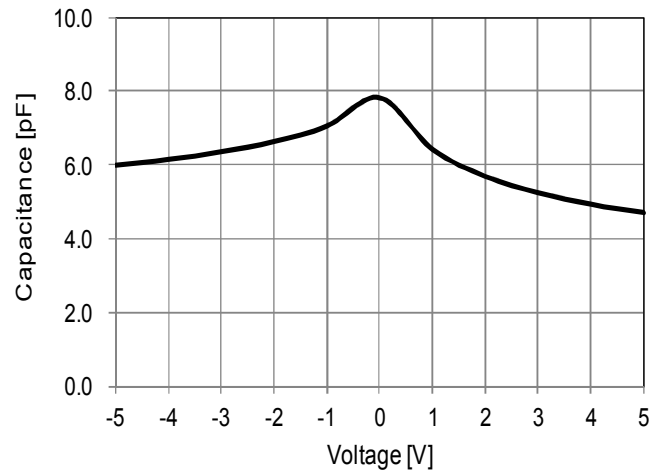


Voltage—Capacitance Characteristic

LXES1UBAA1-096

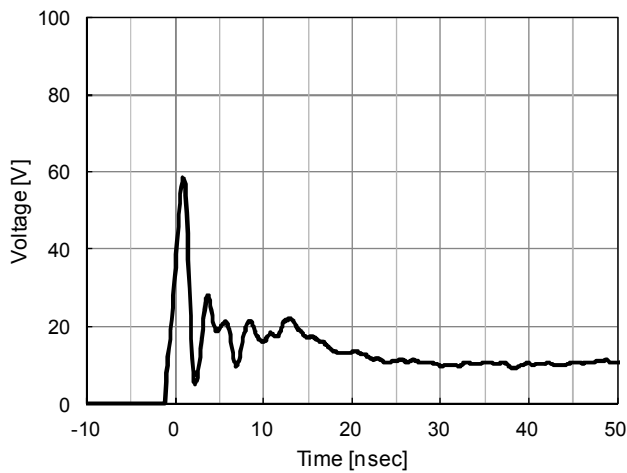


ESD Waveform(IEC61000-4-2:8kV Contact)

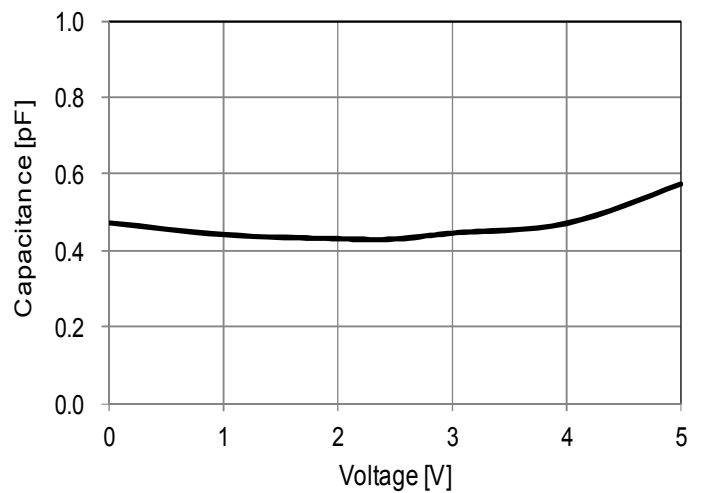


Voltage—Capacitance Characteristic

LXES1TBCC2-004

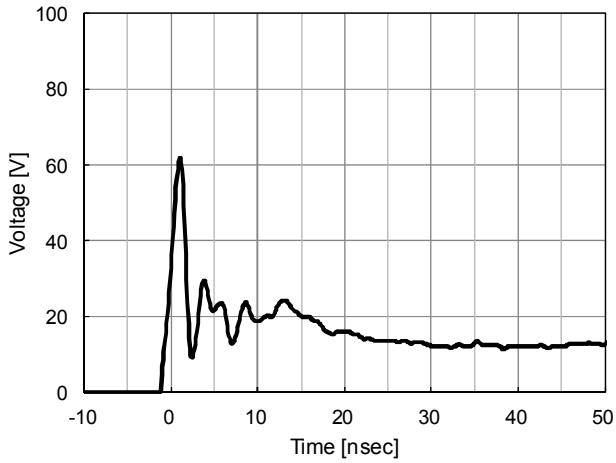


ESD Waveform(IEC61000-4-2:8kV Contact)

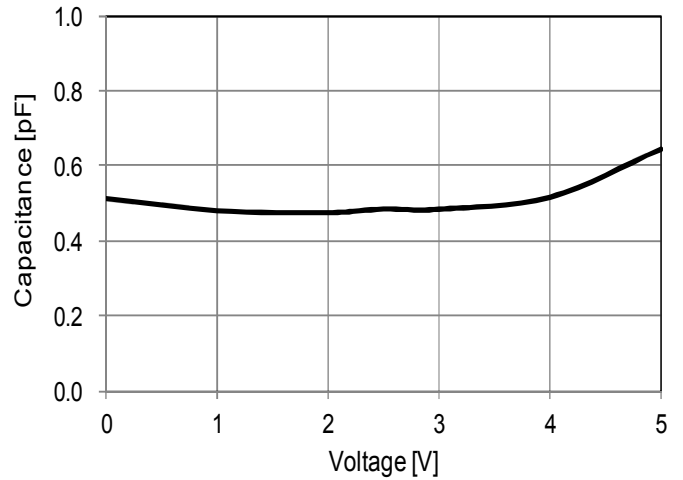


Voltage—Capacitance Characteristic

LXES1TB3B2-013

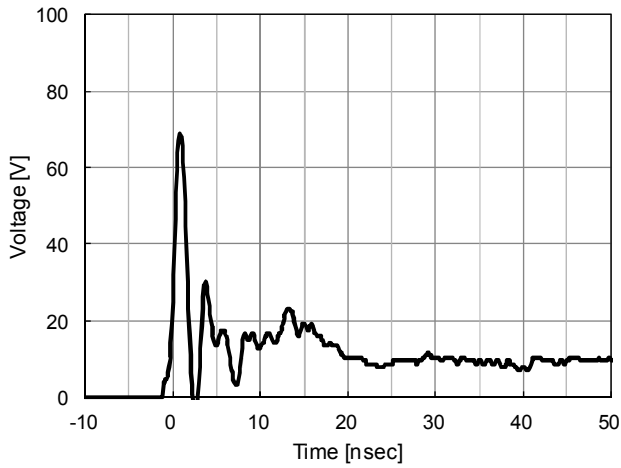


ESD Waveform(IEC61000-4-2:8kV Contact)

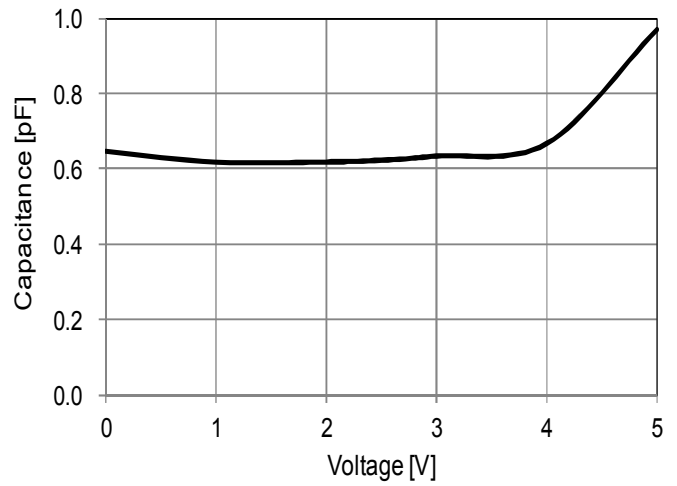


Voltage – Capacitance Characteristic

LXES2SBAA4-016

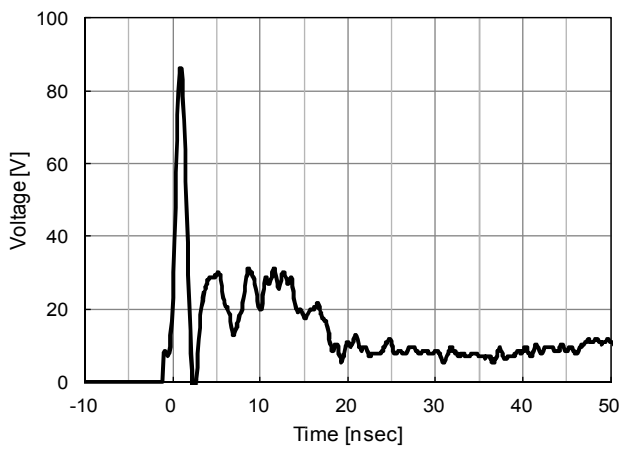


ESD Waveform(IEC61000-4-2:8kV Contact)

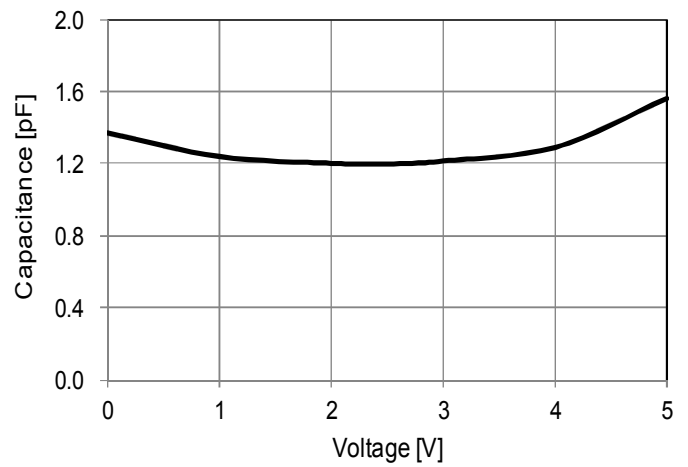


Voltage – Capacitance Characteristic

LXES2SBBB4-026

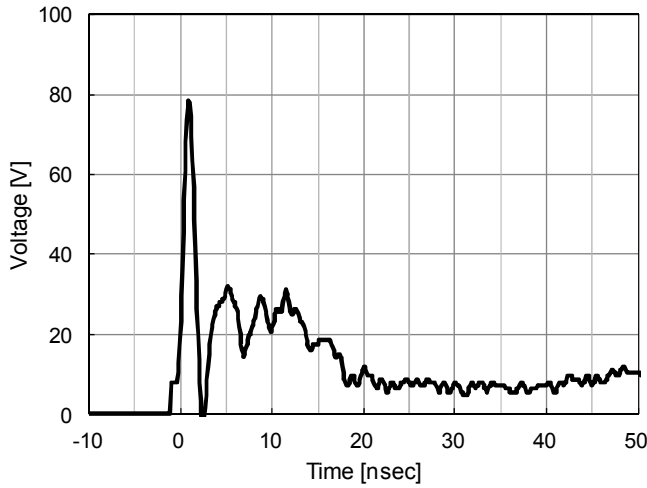


ESD Waveform(IEC61000-4-2:8kV Contact)

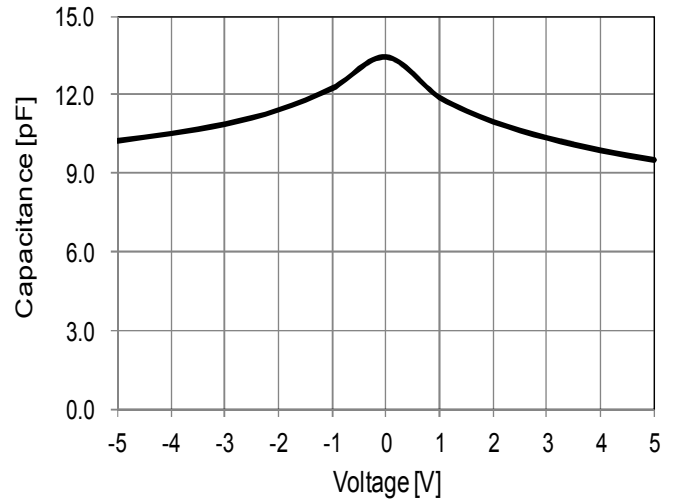


Voltage – Capacitance Characteristic

LXES2SBAA4-114

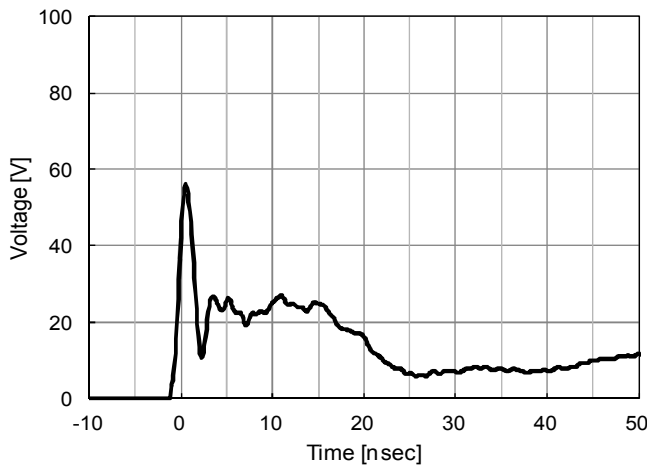


ESD Waveform(IEC61000-4-2:8kV Contact)

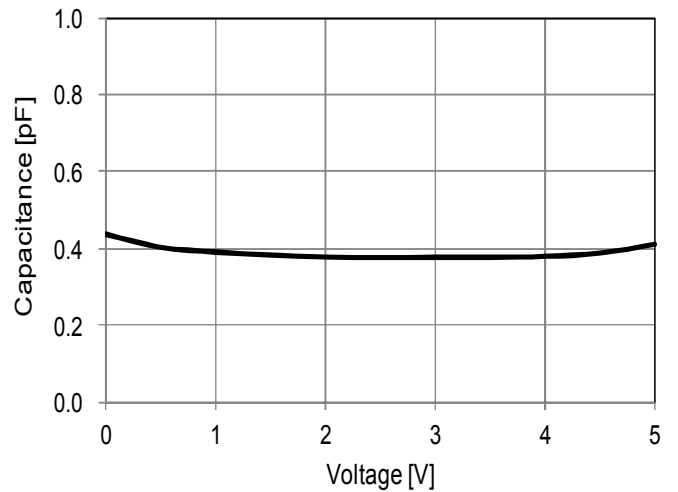


Voltage—Capacitance Characteristic

LXES2TBCC4-028

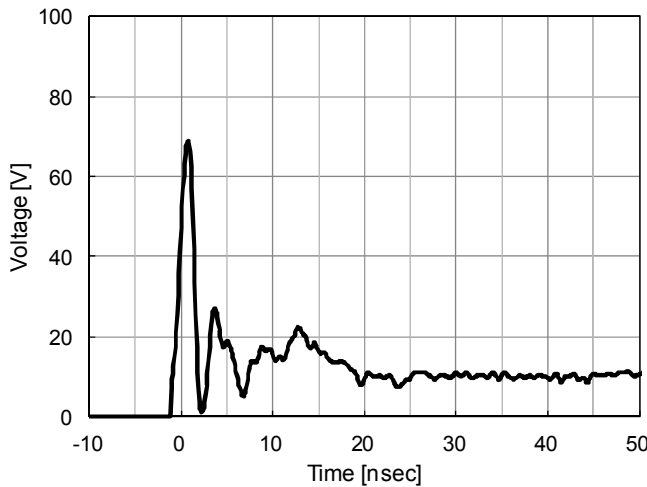


ESD Waveform(IEC61000-4-2:8kV Contact)

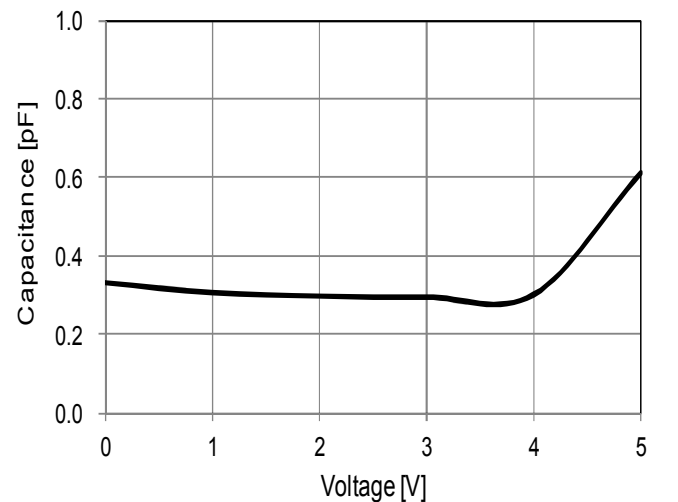


Voltage—Capacitance Characteristic

LXES4XBAA6-027



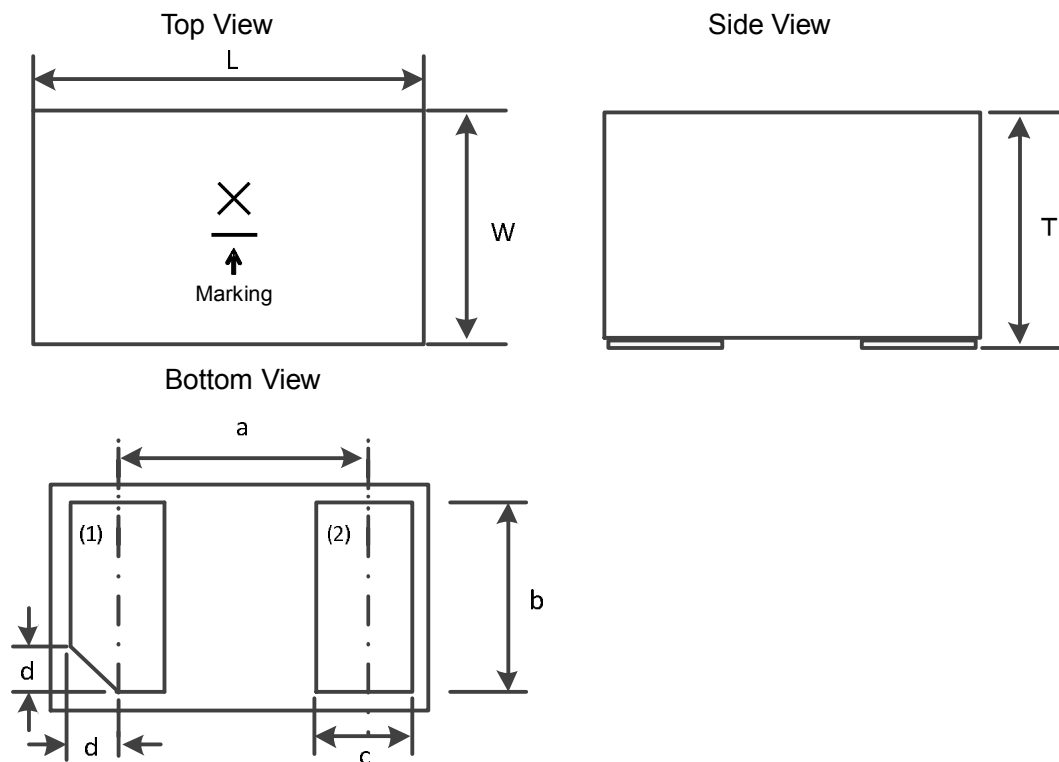
ESD Waveform(IEC61000-4-2:8kV Contact)



Voltage—Capacitance Characteristic

4. CONSTRUCTION, DIMENSIONS
 (1) DFN1006P2E

4 - 1 - 1 DIMENSIONS



Unit : mm

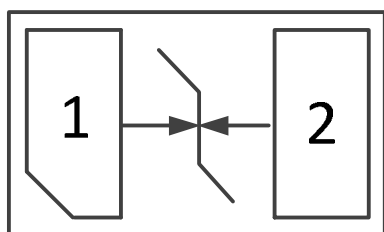
symbol	size
L	1.0+/-0.05
W	0.6+/-0.05
T	0.6 max
a	(0.65)

symbol	size
b	0.5+/-0.05
c	0.25+/-0.05
d	(0.125)

4 - 1 - 2 Pin Configuration

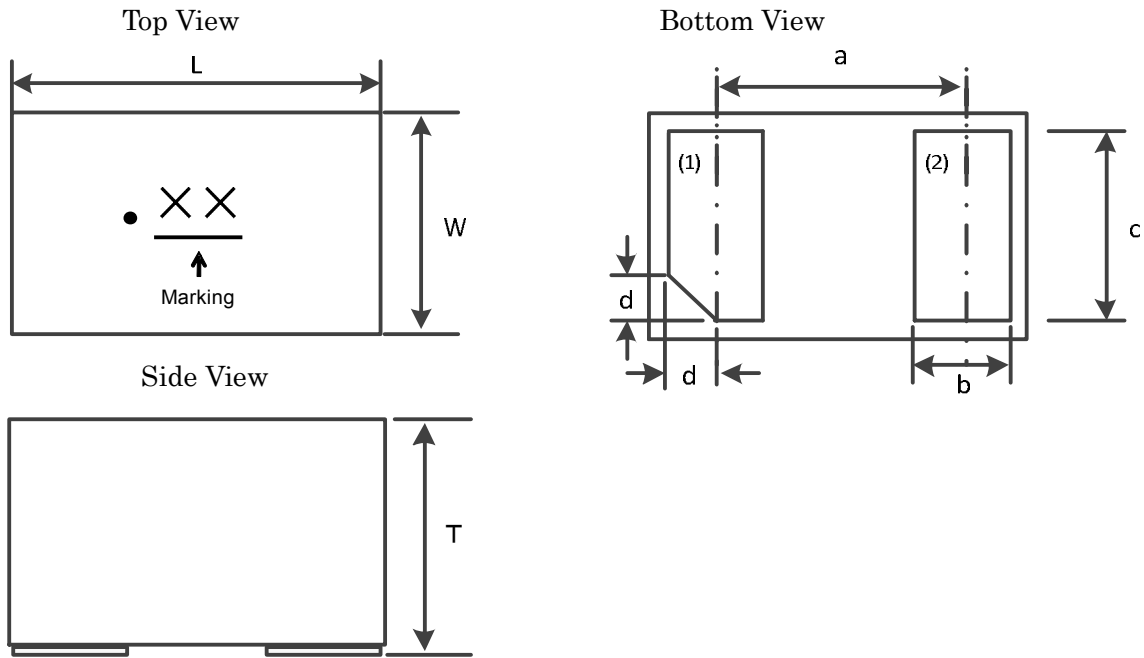
No.	Terminal Name
1	Line-1/GND
2	GND/Line-1

4 - 1 - 3 Circuit Diagram



(2) DFN1006P2X

4 - 2 - 1 DIMENSIONS



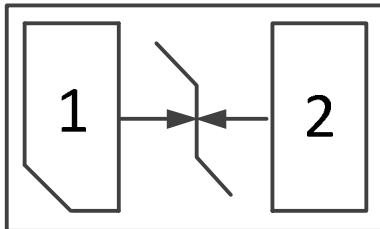
symbol	size
L	1.0+/-0.05
W	0.6+/-0.05
T	0.5 max
a	(0.65)

symbol	size
b	0.25+/-0.05
c	0.50+/-0.05
d	(0.125)

4 - 2 - 2 Pin Configuration

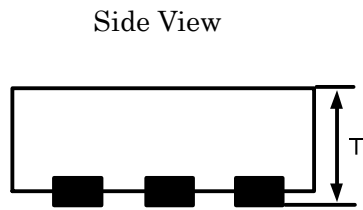
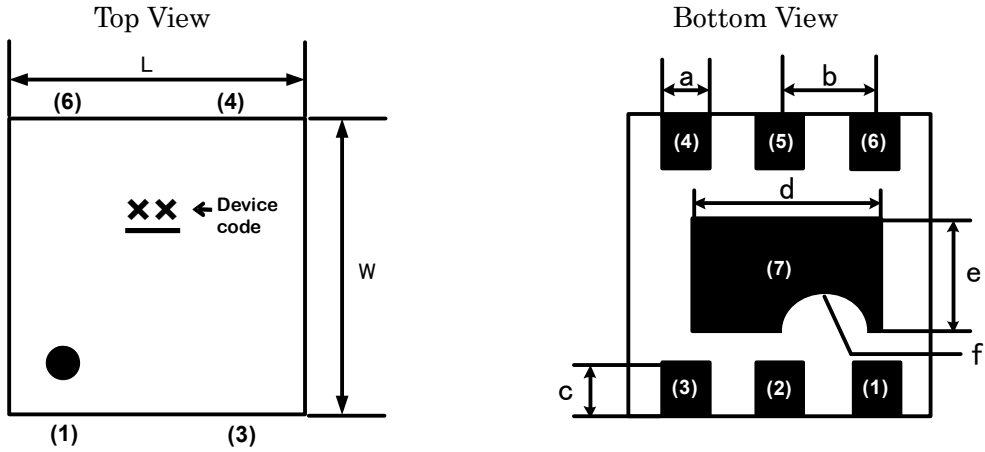
No.	Terminal Name
1	Line-1/GND
2	GND/Line-1

4 - 2 - 3 Circuit Diagram



(3) QFN1616P6E

4 - 3 - 1 DIMENSIONS



symbol	size
L	1.6+/-0.05
W	1.6+/-0.05
T	0.6 max
a	0.25+/-0.05
b	(0.5)

Unit : mm

symbol	size
c	0.275+/-0.05
d	(1.0)
e	(0.6)
f	R0.2

4 - 3 - 2 Pin Configuration

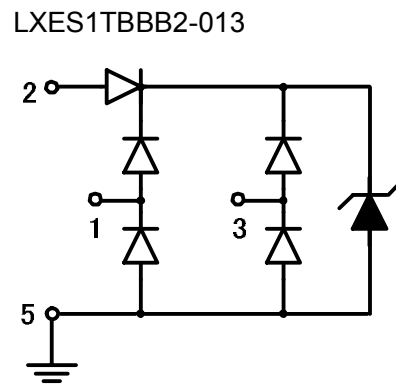
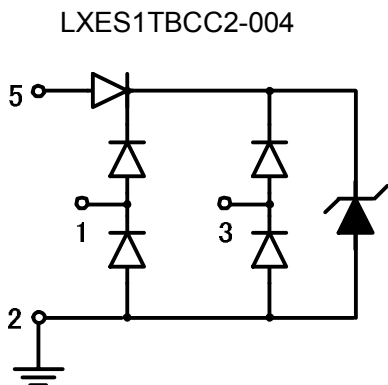
LXES1TBCC2-004

No.	Terminal Name	No.	Terminal Name
1	I/O 1	5	VDD
2	GND	6	NC
3	I/O 2	7	NC
4	NC		

LXES1TBBB2-013

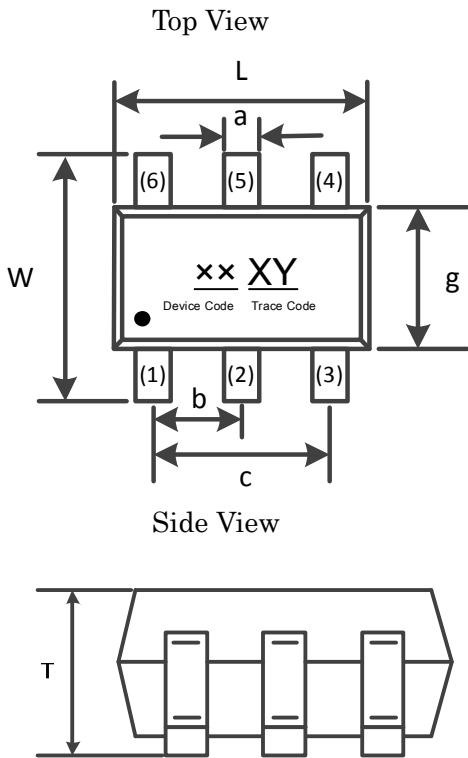
No.	Terminal Name	No.	Terminal Name
1	I/O 1	5	GND
2	VDD	6	NC
3	I/O 2	7	NC
4	NC		

4 - 3 - 3 Circuit Diagram



(4) SOT23-6L

4 - 4 - 1 DIMENSIONS



Bottom View

Unit : mm

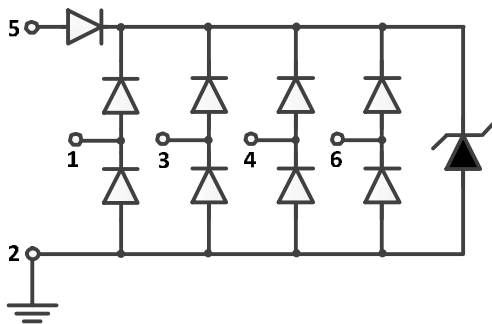
symbol	size
L	2.9 typ
W	2.8 typ
T	1.45 max
a	0.4±0.10
b	(0.95)

symbol	size
c	(1.9)
d	1.3 max
e	0.15 max
f	0.14±0.06
g	(0.6)

4 - 4 - 2 Pin Configuration

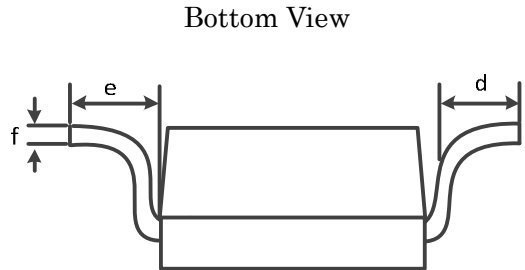
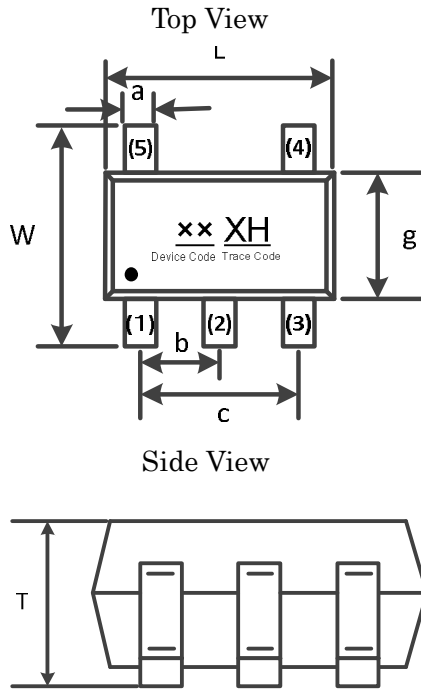
No.	Terminal Name	No.	Terminal Name
1	I/O 1	4	I/O 3
2	GND	5	VDD
3	I/O 2	6	I/O 4

4 - 4 - 3 Circuit Diagram



(5) SOT23-5L

4 - 5 - 1 DIMENSIONS



Unit : mm

symbol	size
L	2.9±0.2
W	2.8±0.2
T	1.45 max
a	0.4±0.10
b	(0.95)

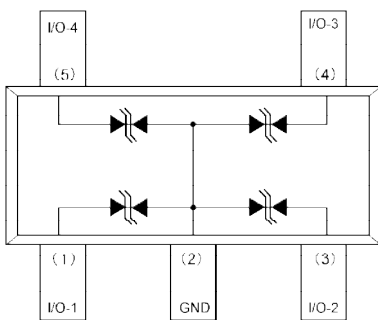
symbol	size
c	(1.9)
d	(0.45)
e	(0.6)
f	0.21 max
g	1.8 max

4 - 5 - 2 Pin Configuration

No.	Terminal Name
1	I/O 1
2	GND
3	I/O 2

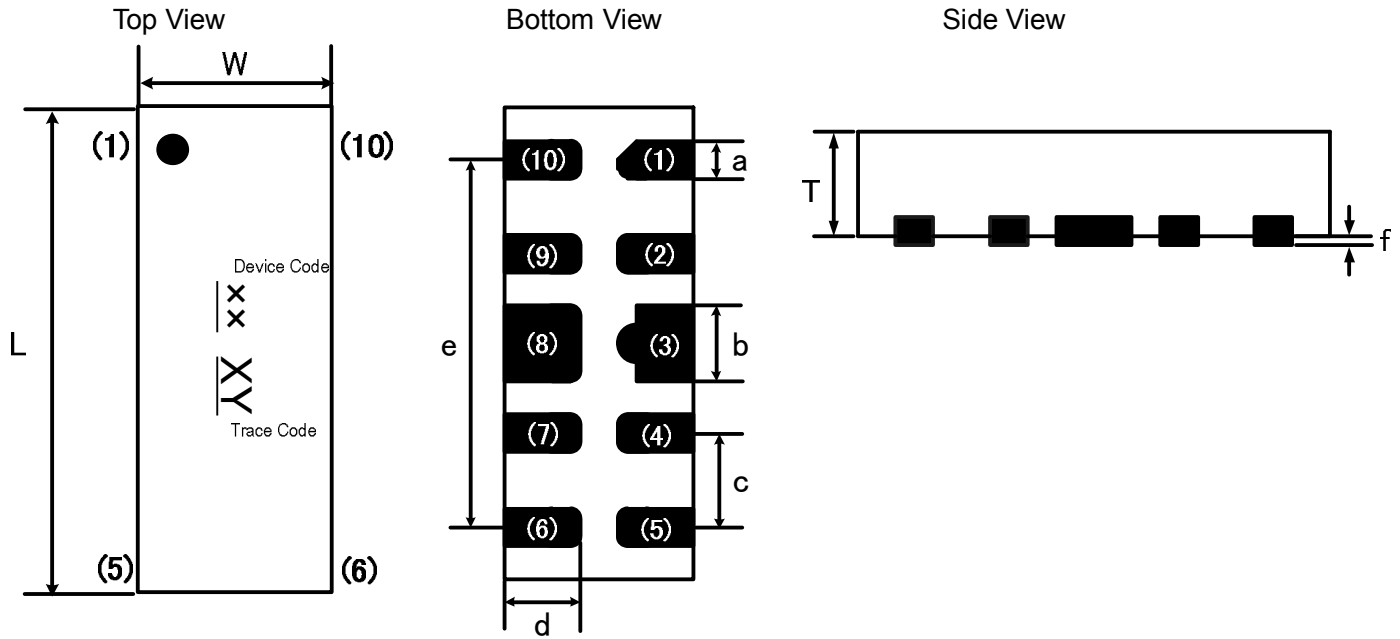
No.	Terminal Name
4	I/O 3
5	I/O 4

4 - 5 - 3 Circuit Diagram



(6) DFN2510P10E

4 - 6 - 1 DIMENSIONS



Unit : mm

symbol	size
L	2.5+/-0.05
W	1.0+/-0.05
T	0.60 max
a	0.20+/-0.05
b	0.40+/-0.05

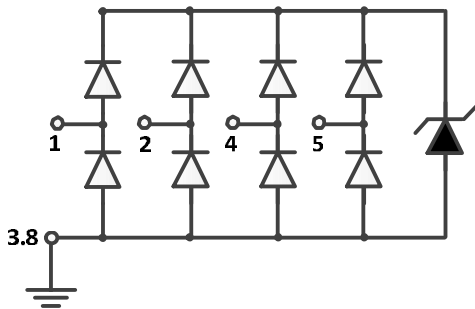
symbol	size
c	(0.5)
d	0.40+/-0.05
e	(1.95)
f	0.05 max

4 - 6 - 2 Pin Configuration

No	Terminal Name
1	Line-1
2	Line-2
3	GND
4	Line-3
5	Line-4

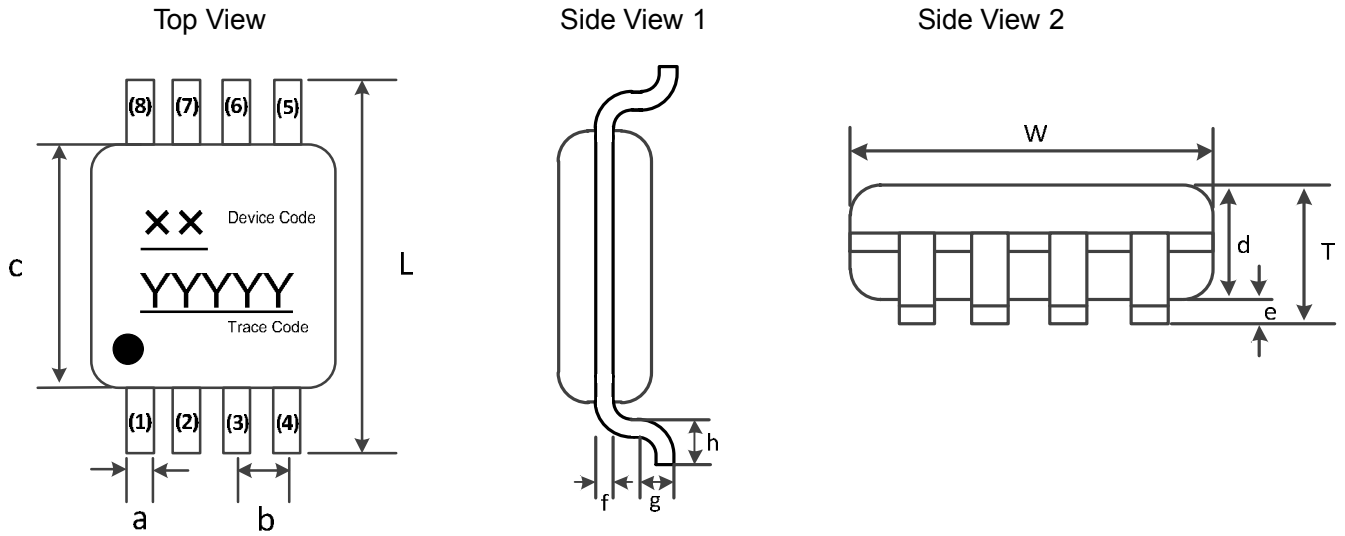
No	Terminal Name
6	NC
7	NC
8	GND
9	NC
10	NC

4 - 6 - 3 Circuit Diagram



(7) MSOP-8L

4 - 7 - 1 DIMENSIONS



Unit : mm

symbol	size
L	4.9+/-0.15
W	3.0+/-0.10
T	1.1 max
a	0.30+0.08/-0.02
b	(0.65)
c	3.0+/-0.10

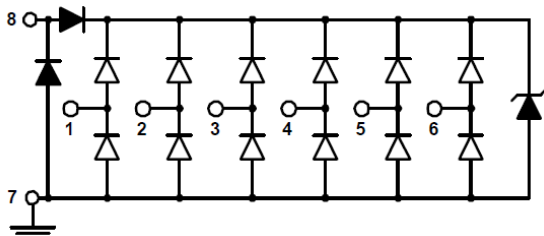
symbol	size
d	0.95 max
e	0.15 max
f	0.15+0.08/-0.02
g	(0.25)
h	(0.55)

4 - 7 - 2 Pin Configuration

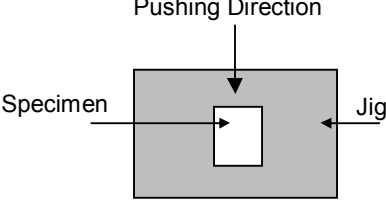
No.	Terminal Name
1	I/O 1
2	I/O 2
3	I/O 3
4	I/O 4

No.	Terminal Name
5	I/O 5
6	I/O 6
7	GND
8	VDD

4 - 7 - 3 Circuit Diagram



5. Reliability Test

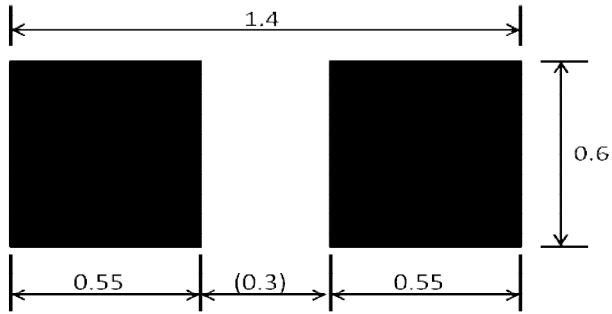
No.	Items		Specifications	Test Methods	Number	Result (Fail)
1	Vibration Resistance		No severe damages Satisfy dimension specifications	Solder specimens on the testing jig (glass fluorine boards) shown in appended Fig.1 by a Pb free solder. The soldering shall be done either by iron or reflow and be conducted with care so that the soldering is uniform and free of defect such as by heat shock. Frequency : 10~2000 Hz Acceleration : 196 m/s ² Direction : X,Y,Z 3 axis Period : 2 h on each direction Total 6 h.	22	G (0)
2	Shock			Solder specimens on the testing jig (glass fluorine boards) shown in appended Fig.1 by a Pb free solder. The soldering shall be done either by iron or reflow and be conducted with care so that the soldering is uniform and free of defect such as by heat shock Acceleration : 14,700 m/s ² Period : 0.3 ms. Cycle : 3 times	22	G (0)
3	Deflection			Solder specimens on the testing jig (glass epoxy boards) shown in appended Fig.2 by a Pb free solder. The soldering shall be done either by iron or reflow and be conducted with care so that the soldering is uniform and free of defect such as by heat shock. No damage with 1.6mm deflection	22	G (0)
4	Soldering strength (Push Strength)		DFN0603P2Y 2N Minimum DFN1006P2E , DFN1006P2X 3N Minimum Others 5N Minimum	Solder specimens onto test jig shown below. Apply pushing force at 0.5mm/s until electrode pads are peeled off or product is broken. Pushing force is applied to longitudinal direction. 	22	G (0)
5	Solderability of Termination		75% of the terminations is to be soldered evenly and continuously.	Immerse specimens first an ethanol solution of rosin, then in a Pb free solder solution for 3±0.5 sec. at 245±5 °C. Preheat : 150 °C, 60 sec. Solder Paste : Sn-3.0Ag-0.5Cu Flux : Solution of ethanol and rosin (25 % rosin in weight proportion)	22	G (0)
6	Resistance to Soldering Heat (Reflow)	Appearance Electrical specifications	No severe damages Satisfy specifications listed in paragraph 3-2 over operational temperature range	Preheat Temperature : 150-180 °C Preheat Period : 90+/-30 s High Temperature : 220 °C High Temp. Period : 30+/-10 s Peak Temperature : 260+5/-0 °C Specimens are soldered twice with the above condition, and then kept in room condition for 24 h before measurements.	22	G (0)

No.	Items		Specifications	Test Methods	Number	Result (Fail)									
7	High Temp. Exposure	Appearance	No severe damages	Temperature : 85±2/-0 °C Period : 1000+48/-0 h Room Condition : 2 ~ 24 h	22	G (0)									
8	Temperature Cycle	Electrical Specifications	Satisfy specifications listed in paragraph 3-2 over operational temperature range	Set the specimens to the supporting jig in the same manner and under the same conditions as Fig.1 and conduct the 100 cycles according to the temperatures and time shown in the following table. Set it for 2 to 24 h at room temperature, then measure.	22	G (0)									
				<table border="1"> <thead> <tr> <th>Step</th> <th>Temp(°C)</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Min. Operating Temp.+0/-3</td> <td>30±3</td> </tr> <tr> <td>2</td> <td>Max. Operating Temp.+3/-0</td> <td>30±3</td> </tr> </tbody> </table>			Step	Temp(°C)	Time(min)	1	Min. Operating Temp.+0/-3	30±3	2	Max. Operating Temp.+3/-0	30±3
Step	Temp(°C)			Time(min)											
1	Min. Operating Temp.+0/-3			30±3											
2	Max. Operating Temp.+3/-0	30±3													
		Temperature: 85±2 °C Humidity: 80~90 %RH Period: 1000+48/-0 h Room Condition: 2 ~ 24 h													
		Temperature: -40±2 °C Period: 1000+48/-0 h Room Condition: 2 ~ 24 h													
9	Humidity (Steady State)			Temperature: 85±2 °C Humidity: 80~90 %RH Period: 1000+48/-0 h Room Condition: 2 ~ 24 h	22	G (0)									
10	Low Temp. Exposure			Temperature: -40±2 °C Period: 1000+48/-0 h Room Condition: 2 ~ 24 h	22	G (0)									

Fig. 1 Land Pattern

Package : DFN1006P2E , DFN1006P2X

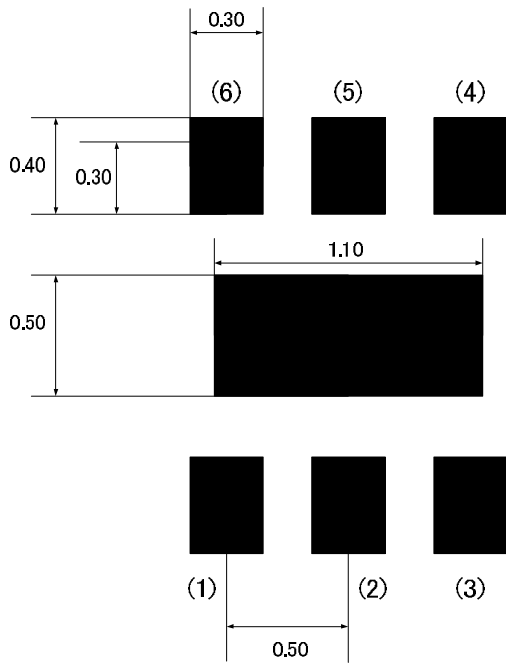
Unit : mm



※Reference purpose only.

Package : QFN1616P6E

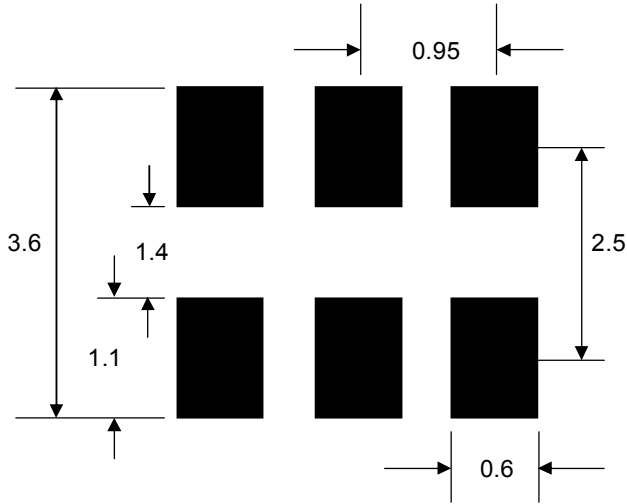
Unit : mm



※Reference purpose only.

Package : SOT23-6L

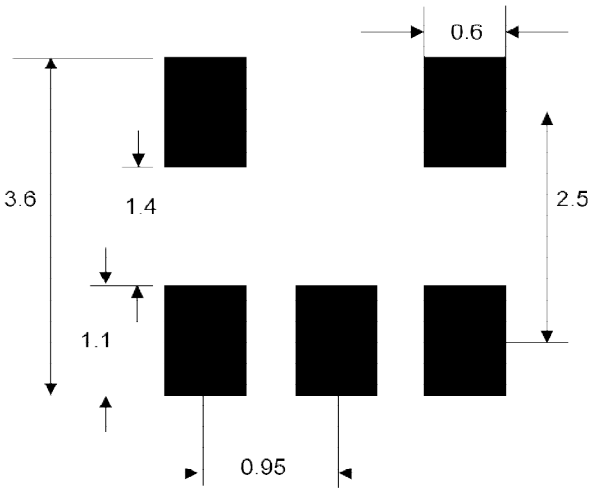
Unit : mm



※Reference purpose only.

Package : SOT23-5L

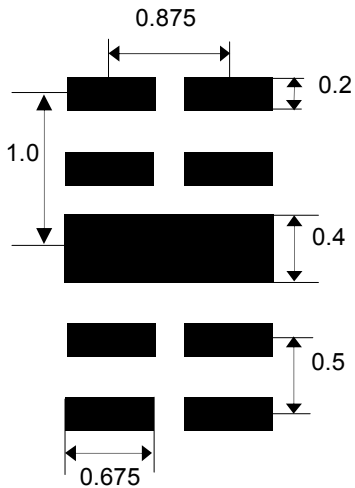
Unit : mm



※Reference purpose only.

Package : DFN2510P10E

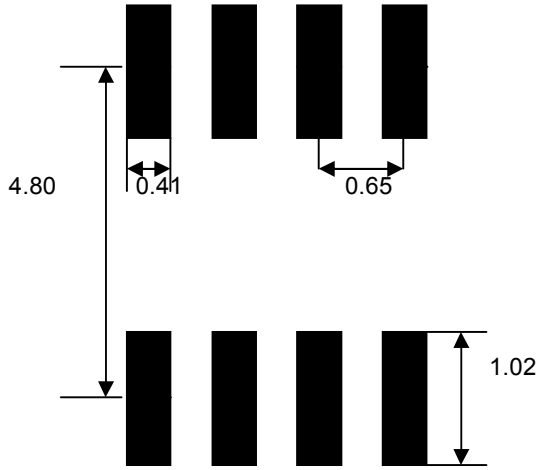
Unit : mm



※Reference purpose only.

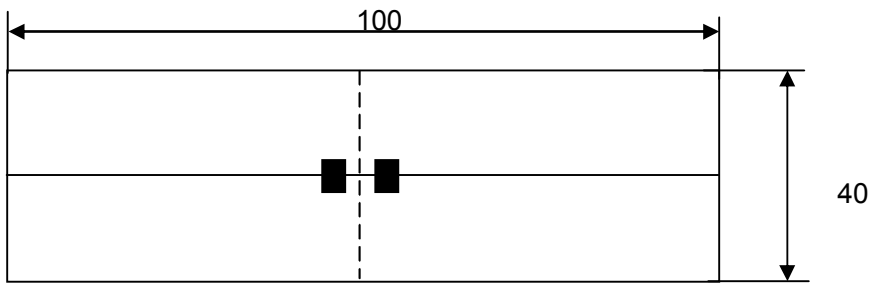
Package : MSOP-8L

Unit : mm



※Reference purpose only.

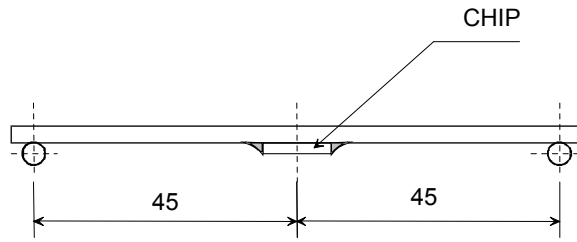
Fig. 2 Testing board



(Unit : mm)

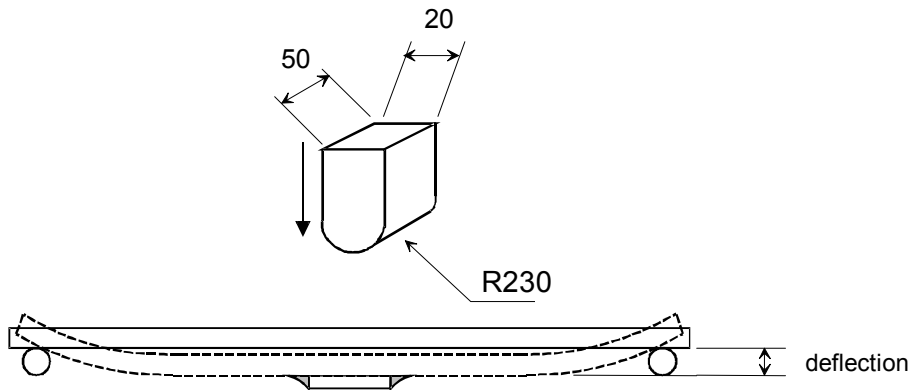
■ Land
Land pattern is same as figure 1
Glass-fluorine board $t=1.6\text{mm}$
Copper thickness over $35\ \mu\text{m}$

Mounted situation



(Unit : mm)

Test method

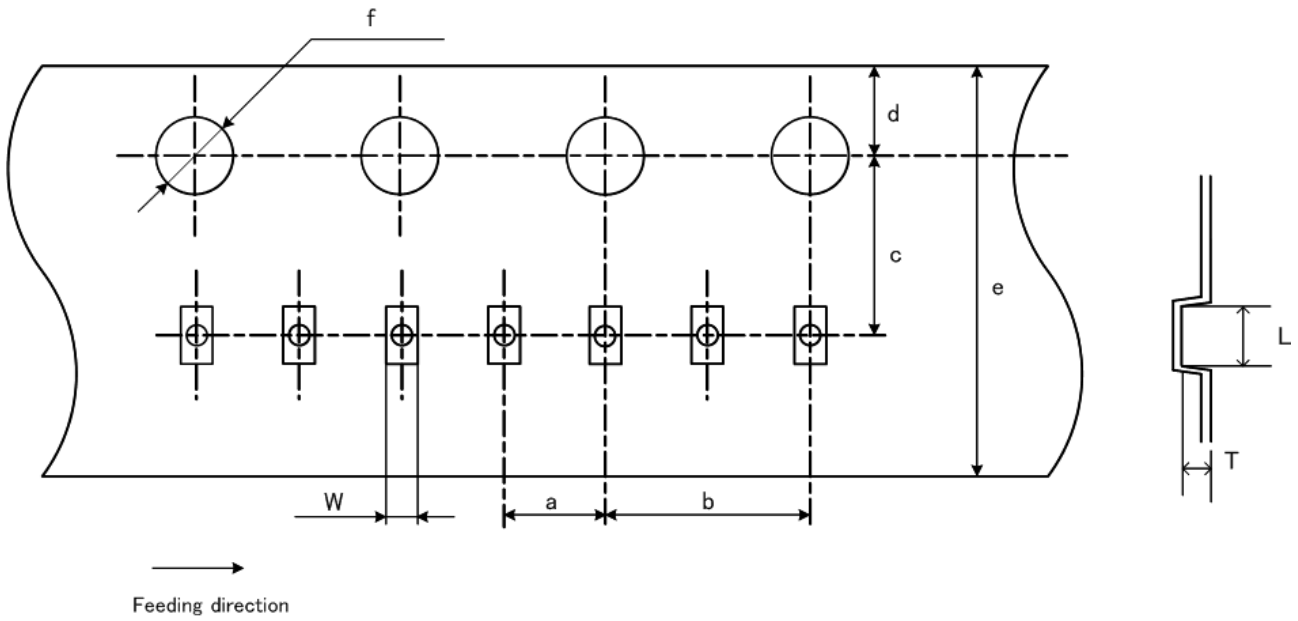


(Unit : mm)

6. Tape and Reel Packing

(1) Dimensions of Tape (Plastic tape)

Not in scale

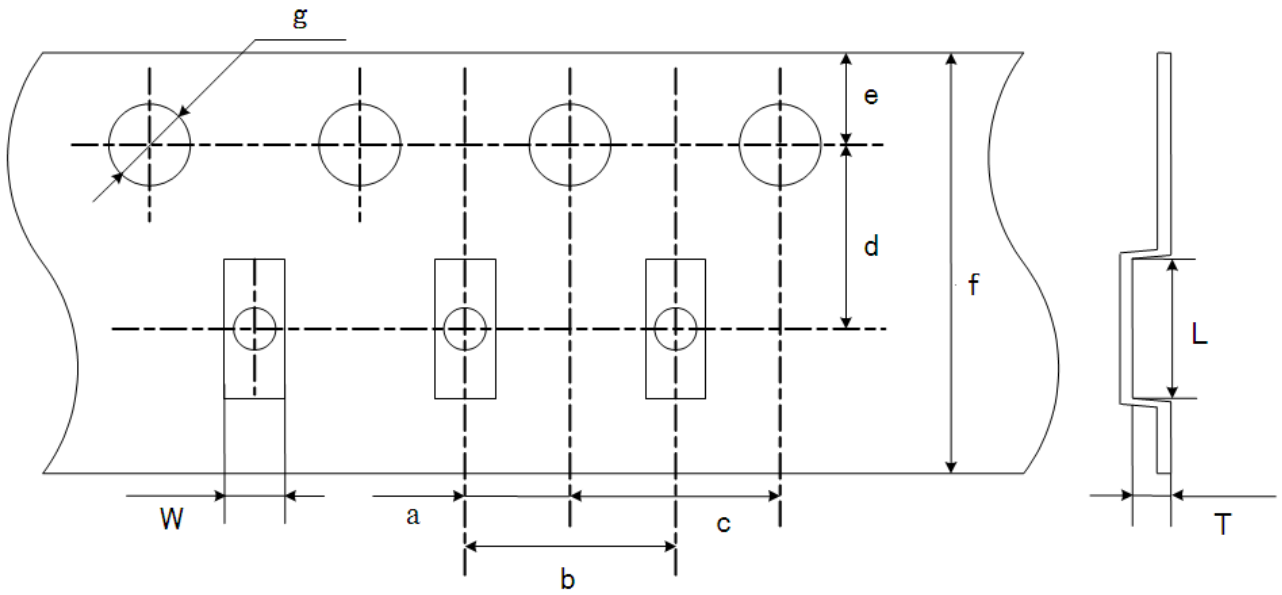


Unit : mm

package	DFN1006P2E	DFN1006P2X
L	(1.10)	(1.15)
W	(0.70)	(0.70)
T	(0.65)	(0.52)
a	2.00+/-0.05	2.00+/-0.05
b	4.00+/-0.10	4.00+/-0.10
c	3.50+/-0.05	3.50+/-0.05
d	1.75+/-0.1	1.75+/-0.1
e	8.00+0.30/-0.10	8.00+/-0.10
f	ϕ 1.55+/-0.05	ϕ 1.55+/-0.05

(2) Dimensions of Tape (Plastic tape)

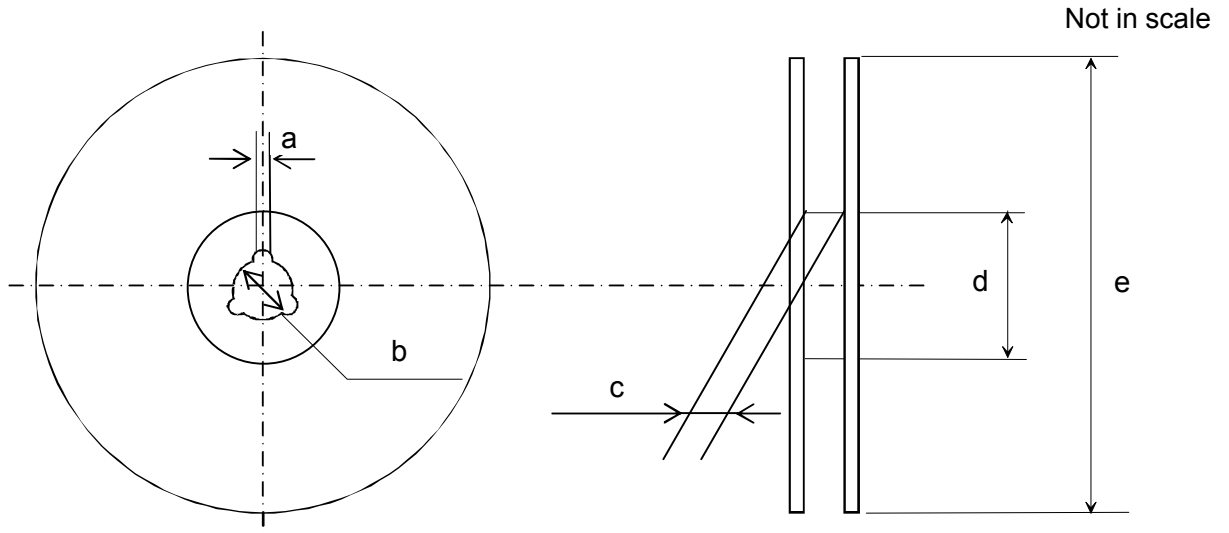
Not in scale



Unit : mm

package	QFN1616P6E	SOT23-6L	SOT23-5L	DFN2510P10E	MSOP-8L
L	1.80+/-0.05	3.23+/-0.10	3.23+/-0.10	2.70+/-0.05	3.40+/-0.10
W	1.80+/-0.05	3.17+/-0.10	3.17+/-0.10	1.23+/-0.05	5.30+/-0.10
T	0.69+/-0.05	1.37+/-0.10	1.37+/-0.10	0.70+/-0.05	1.40+/-0.10
a	2.00+/-0.05	2.00+/-0.05	2.00+/-0.05	2.00+/-0.05	2.00+/-0.05
b	4.00+/-0.10	4.00+/-0.10	4.00+/-0.20	4.00+/-0.10	8.00+/-0.10
c	4.00+/-0.10	4.00+/-0.10	4.00+/-0.10	4.00+/-0.10	4.00+/-0.10
d	3.50+/-0.05	3.50+/-0.05	3.50+/-0.05	3.50+/-0.05	5.50+/-0.05
e	1.75+/-0.1	1.75+/-0.1	1.75+/-0.1	1.75+/-0.1	1.75+/-0.10
f	8.00+/-0.10	8.00+0.30/-0.10	8.00+0.30/-0.10	8.00+0.30/-0.20	12.0+/-0.30
g	φ1.55+/-0.05	φ1.55+/-0.05	φ1.55+/-0.05	φ1.55+/-0.05	φ1.55+/-0.05

(3) Dimensions of Reel



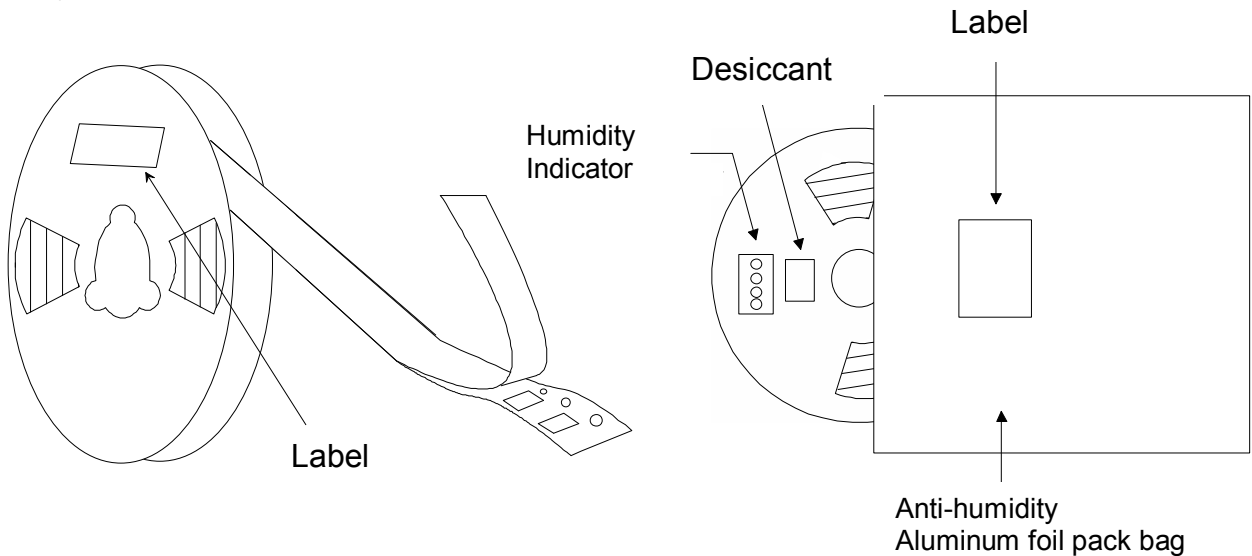
Unit : mm

package	DFN1006P2E	DFN1006P2X	QFN1616P6E	SOT23-6L
a	1.5 min	1.5 min	2.3+/-0.1	2.3+/-0.1
b	φ13.0+/-0.2	φ13.0+/-0.2	φ13.0+/-0.2	φ13.0+/-0.2
c	9.2+2.0/-0	9.2+2.0/-0	9.5+/-1.0	9.5+/-1.0
d	φ60	φ60	φ54.4	φ60
e	φ180	φ180	φ180	φ180

package	SOT23-5L	DFN2510P10E	MSOP-8L
a	2.0+0.5/-0	2.3+/-0.1	2.0+/-0.5
b	φ13.0+0.5/-0.3	φ13.0+/-0.2	φ13.0+0.5/-0.2
c	8.6+1.0/-0	9.5+/-0.2	12.8+0.3/-0.2
d	φ54.4	φ60	φ100
e	φ180	φ180	φ330

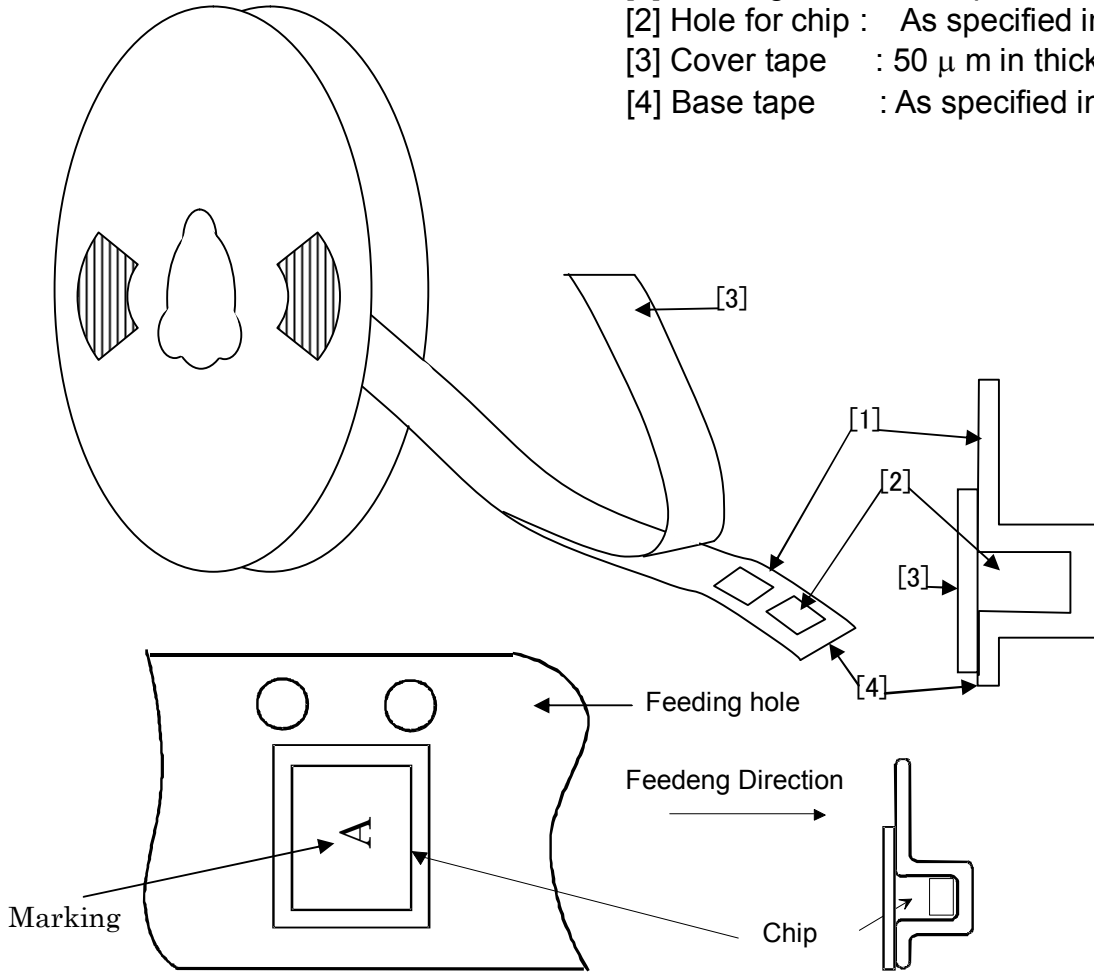
(4) PACKAGE Diagrams (Humidity proof Packing)

Tape and reel must be sealed with the anti-humidity plastic bag. The bag contains the desiccant and the humidity indicator.



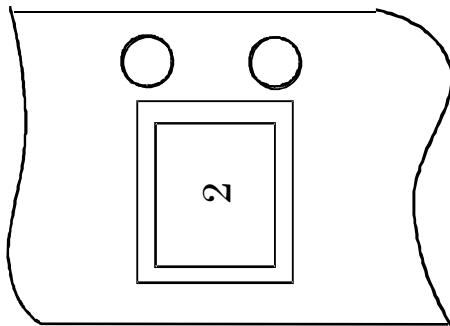
(5) Taping Diagrams

- [1] Feeding Hole : As specified in (1),(2)
- [2] Hole for chip : As specified in (1),(2)
- [3] Cover tape : 50 μ m in thickness
- [4] Base tape : As specified in (1),(2)

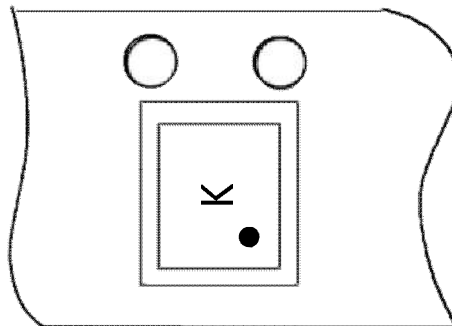


Marking Direction

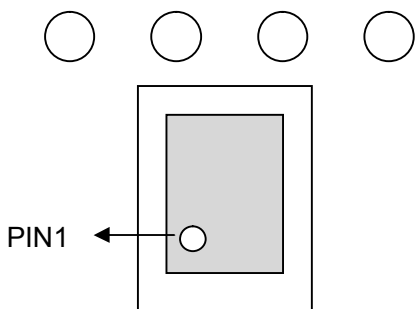
LXES1UBAB1-007



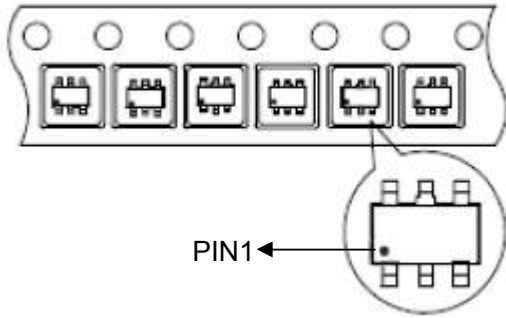
LXES1UBAA1-096



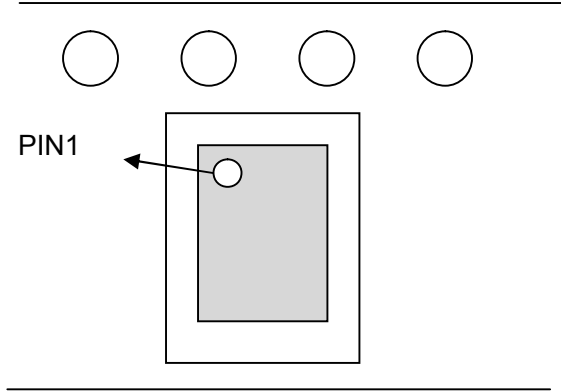
LXES1TBCC2-004/LXES1TBBB2-013



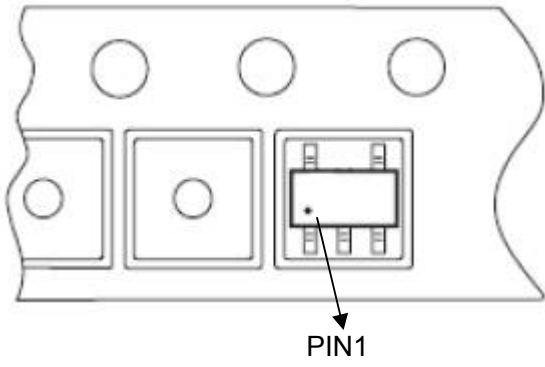
LXES2SBAA4-016/LXES2SBBB4-026



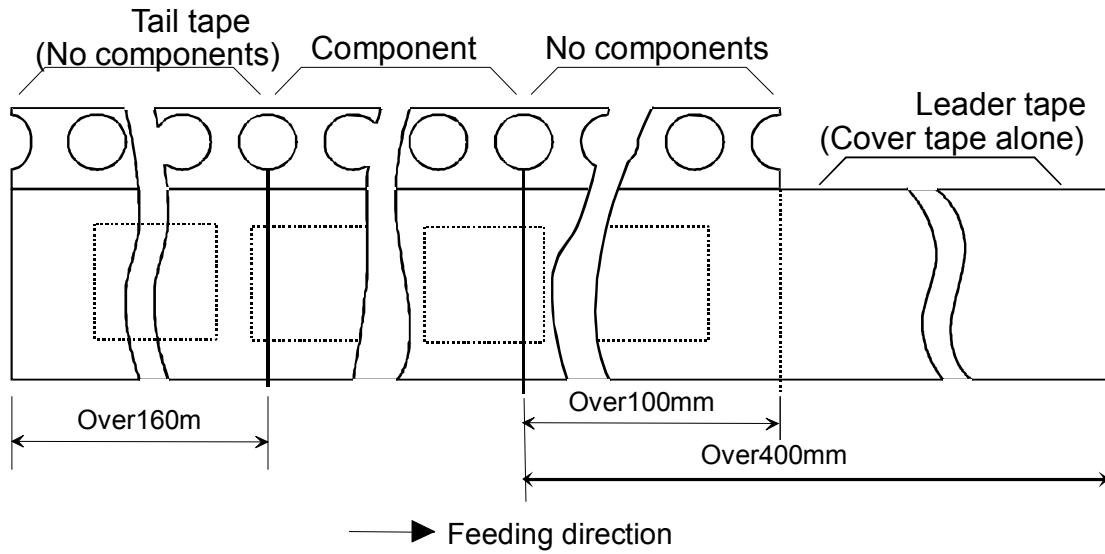
LXES4XBAA6-027/ LXES2TBCC4-028/



LXES2SBAA4-114



(6) Leader and Tail tape



(7) The tape for chips are wound clockwise, the feeding holes to the right side as the tape is pulled toward the user.

(8) Packaging unit:

Unit : pcs / reel

package	DFN1006P2E	DFN1006P2X	QFN1616P6E	SOT23-6L
quantity	3000	12000	3000	3000

package	SOT23-5L	DFN2510P10E	MSOP-8L	DFN4120P10E
quantity	3000	3000	3000	3000

(9) Material : Base tape Plastic
 ReelPlastic

Base tape, Reel and Top tape have an anti-ESD function.

(10) Peeling of force : 0.1~1.0 N in the direction of peeling as shown below.

